



Product Change Notification

108110 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108110 - 00
Change Title: Intel® G33, P35, Q33, Q35, G31 & P31 Express Chipsets, PCN 108110-00, Product Material, Removal of the paste stencil apertures for the non function pads
Date of Publication: December 11, 2007

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

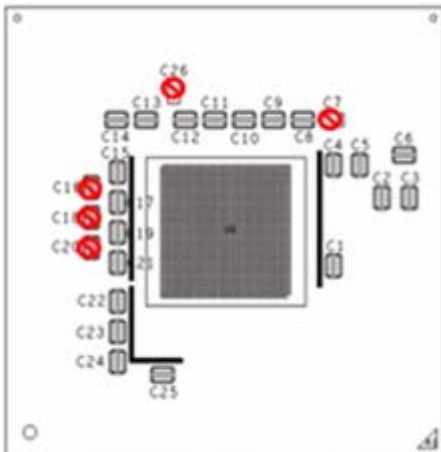
Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 11, 2008
Date of First Availability of Post-Conversion Material:	Jan 11, 2008

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

The paste stencil apertures for non function pads will be removed for the Intel® 3 Series Express Chipset FCBGA7 products. Products include Intel® Q35, Q33, G33, P35, G31, and P31 Express Chipsets. The previous stencil had openings that allowed solder paste to be added to those pads though no capacitors were placed there.

The drawing below shows (in red) where the previous stencil openings were that will be removed.



Customer Impact of Change and Recommended Action:

Non Function Pads will have solder paste removed showing the gold colored pad. Removal of solder paste will improve reliability by greatly reducing the risk of solder bridging across the capacitor pads, during the reflow process.

No impact on product functionality is currently expected.

Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#
Intel® G33 Express Chipset	A-2	LE82G33	S LA9Q	890312
Intel® P35 Express Chipset	A-2	LE82P35	S LA9R	890313
Intel® Q33 Express Chipset	A-2	LE82Q33	S LAEW	891053
Intel® Q35 Express Chipset	A-2	LE82Q35	S LAEX	891054
Intel® P31 Express Chipset	A-2	LE82P31	S LAHX	892044
Intel® G31 Express Chipset	A-2	LE82G31	S LAJ3	892056

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

Revision Number:

Reason:

December 11, 2007

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Originally Published PCN